edtm 2023
Electron Devices Technology and Manufacturing Conference

7th IEEE Electron Devices Technology and Manufacturing (EDTM) Conference 2023

March 7 – 10, 2023 / COEX Seoul, Korea

1A. Advanced Interconnect for Packaging	
Session Date:	March 8(Wed.), 2023
Session Time:	10:55-12:30
Session Room:	Room A (#301)
Session Chair	Prof. Taek-Soo Kim (Korea Advanced Institute of Science and Technology)

[1A-1] [Keynote] 10:55-11:20

AI Semiconductor Chips Using Heterogeneous Integration: Why the Hype and What Next?

Sung Kyu Lim

Georgia Institute of Technology

[1A-2] [Invited] 11:20-11:45

Flip Chip Joining with Injection Molded Solder Technology

Takashi Hisada and Toyohiro Aoki

IBM Japan Ltd.

[1A-3] 11:45-12:00

Erosion Improvement through Chemical-Mechanical-Polishing (CMP) Process Control for the Application of Cu Hybrid Bonding

Jihye Lee, Wooseok Seo, Jaehyung Lim, Mincheol Kang, Youngsu Yun, Hyuk Kwon, Jinwon Park, Gyuhyun Kim and Jiho Kang

SK hynix

[1A-4] 12:00-12:15

Study on the Application of Gallium as an Interconnection Material for Microelectronic Packaging

Yoonchul Sohn

Chosun University

[1A-5] 12:15-12:30

Low Temperature SiCN as Dielectric for Hybrid Bonding

Venkat Sunil Kumar Channam[1], Serena Iacovo[1], Edward Walsby[2], Igor Belov[2], Anne Jourdain[1], Alfonso Sepulveda[1] and Eric Beyne[1]

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